WHAT IS CLAIMED IS:

1. For use with an integrated circuit package having first and second signal transmission zones, a characteristic impedance equalizer, comprising:

a first conductor having a first width and providing a characteristic impedance within said first signal transmission zone; and

a second conductor, coupled to said first conductor, having a second width and providing substantially said characteristic impedance within said second signal transmission zone.

2. The characteristic impedance equalizer as recited in Claim 1 further comprising a plurality of said first and second conductors coupled to a substrate.

3. The characteristic impedance equalizer as recited in Claim 1 wherein said first signal transmission zone is provided between a portion of said substrate containing said first conductor and a metallic heatspreader.

4. The characteristic impedance equalizer as recited in Claim 1 wherein said second signal transmission zone is provided between a portion of said substrate containing said second conductor and a metallic stiffener.

5. The characteristic impedance equalizer as recited in Claim 1 wherein said first width is greater than said second width.

6. The characteristic impedance equalizer as recited in Claim 1 wherein a junction between said first conductor and said second conductor has a semi-circular cross-sectional area.

7. The characteristic impedance equalizer as recited in Claim 1 wherein said first and second conductors provide a transmission path for a signal transmission.

8. A method of manufacturing an integrated circuit package, comprising:

providing a substrate configured to be partitioned into first and second signal transmission zones;

forming a first conductor having a first width and providing a characteristic impedance within said first signal transmission zone; and

forming a second conductor having a second width and providing substantially said characteristic impedance within said second signal transmission zone.

9. The method of manufacturing as recited in Claim 8 further comprising forming a plurality of said first and second conductors.

10. The method of manufacturing as recited in Claim 8 further comprising positioning a metallic heatspreader over a portion of said substrate containing said first conductor and forming said first signal transmission zone.

11. The method of manufacturing as recited in Claim 8 further comprising positioning a metallic stiffener over a portion of said substrate containing said second conductor and forming said second signal transmission zone.

12. The method of manufacturing as recited in Claim 8 wherein said first width is greater than said second width.

13. The method of manufacturing as recited in Claim 8 further comprising forming a junction between said first conductor and said second conductor having a semi-circular cross-sectional area.

14. The method of manufacturing as recited in Claim 8 wherein said first and second conductors provide a transmission path for a signal transmission.

15. An integrated circuit package, comprising:

a substrate configured to be partitioned into first and second signal transmission zones; and

a characteristic impedance equalizer, including:

a first conductor having a first width providing a characteristic impedance within said first signal transmission zone, and

a second conductor having a second width providing substantially said characteristic impedance within said second signal transmission zone.

16. The integrated circuit package as recited in Claim 15 wherein said characteristic impedance equalizer contains a plurality of said first and second conductors.

17. The integrated circuit package as recited in Claim 15 further comprising a metallic heatspreader and said first signal transmission zone is provided between a portion of said substrate containing said first conductor and said metallic heatspreader.

18. The integrated circuit package as recited in Claim 15 further comprising a metallic stiffener and said second signal transmission zone is provided between a portion of said substrate containing said second conductor and said metallic stiffener.

19. The integrated circuit package as recited in Claim 15 wherein said first width is greater than said second width.

20. The integrated circuit package as recited in Claim 15 wherein a junction between said first conductor and said second conductor has a semi-circular cross-sectional area.

21. The integrated circuit package as recited in Claim 15 wherein said first and second conductors provide a transmission path for a signal transmission.